

IN THE SPECIFICATION:

Please replace paragraph [0010] with the following amended paragraph:

[0010] An apparatus and method for using ~~[[a]]~~ an adjusted evaporation section area of heat pipe that is sized to match the surface area of an integrated heat spreader used in CPU packages in mobile computers is disclosed. In the following detailed description, numerous specific details are set forth in order to provide a thorough understanding of the present invention. However, it will be apparent to one of ordinary skill in the art that these specific details need not be used to practice the present invention. In other circumstances, well-known structures, materials, or processes have not been shown or described in detail in order not to unnecessarily obscure the present invention.

Please replace paragraphs [0014]-[0015] with the following amended paragraphs:

[0014] Silicon die 114 may be an electronic or digital device, such as a microprocessor. As shown in FIG. 1, silicon die 114 may be attached on the area 115 of a CPU package substrate 108 ~~[[118]]~~, which has a width 118 approximately equal to or slightly greater than the width 116 of heat spreader 109. Depending on the embodiment, the top surface of ~~[[PCB]]~~ the CPU package substrate 108 may have a surface approximately equal to or greater than a surface area associated with the bottom surface of heat spreader 109.

[0015] Referring to FIGS. 1 and 2, cooling apparatus 120 operates in the conventional manner. Current is applied via ~~PCB-109~~ CPU package substrate 108 to silicon die 114 such that the electronic or digital device performs predetermined tasks and operations,

such as floating point operations, for example. Heat 210 generated during operation of device 114 flows through heat spreader 109 (209 in FIG. 2) where it is absorbed by heat absorber 101 (201 in FIG. 2) and thermally conducted along adiabatic region 202 of base 112 (212 in FIG. 2) into a plurality of fins 107 (207 in FIG. 2) attached to the bottom surface of heat dissipating region 203. Air moving past fins 107 dissipates the heat 206 accumulated in fins 107. In this manner, the temperature of heat producing device 114 may be lowered or kept within acceptable operating tolerances.

Please replace paragraph [0020] with the following amended paragraph:

[0020] Thus, an apparatus and method for using ~~[[a]]~~ an adjusted evaporation section area of heat pipe that is sized to match the surface area of an integrated heat spreader used in CPU packages in mobile computers is disclosed. Although the present invention is described herein with reference to a specific preferred embodiment, many modifications and variations therein will readily occur to those with ordinary skill in the art. Accordingly, all such variations and modifications are included within the intended scope of the present invention as defined by the following claims.